

## N-Ch 40V Fast Switching MOSFETs

### Features:

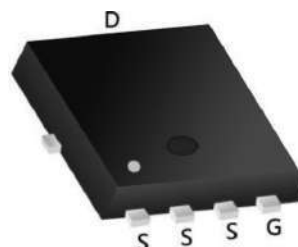
- ★ 100% UIS Tested
- ★ Advanced Trench Technology
- ★ Low Gate Charge
- ★ RoHS and Halogen-Free Compliant

### Applications

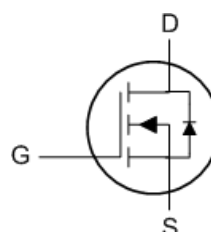
- SMPS Synchronous Rectification
- DC/DC Converters
- Or-ing

### Product Summary

| BVDSS | RDSON | ID  |
|-------|-------|-----|
| 40V   | 6.5mΩ | 45A |



PRPAK5X6 Pin Configuration



### Absolute Maximum Ratings

| Symbol                  | Parameter                                  | Rating     | Units      |
|-------------------------|--------------------------------------------|------------|------------|
| $V_{DS}$                | Drain-Source Voltage                       | 40         | V          |
| $V_{GS}$                | Gate-Source Voltage                        | $\pm 20$   | V          |
| $I_{D@T_C=25^\circ C}$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 45         | A          |
| $I_{D@T_C=100^\circ C}$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 29         | A          |
| $I_{DM}$                | Pulsed Drain Current <sup>2</sup>          | 90         | A          |
| EAS                     | Single Pulse Avalanche Energy <sup>3</sup> | 68         | mJ         |
| $I_{AS}$                | Avalanche Current                          | 37         | A          |
| $P_D@T_C=25^\circ C$    | Total Power Dissipation <sup>4</sup>       | 21         | W          |
| $T_{STG}$               | Storage Temperature Range                  | -55 to 150 | $^\circ C$ |
| $T_J$                   | Operating Junction Temperature Range       | -55 to 150 | $^\circ C$ |

### Thermal Data

| Symbol          | Parameter                                        | Typ. | Max. | Unit         |
|-----------------|--------------------------------------------------|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient <sup>1</sup> | ---  | 65   | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 6    | $^\circ C/W$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Symbol       | Parameter                                      | Conditions                                     | Min. | Typ. | Max.      | Unit      |
|--------------|------------------------------------------------|------------------------------------------------|------|------|-----------|-----------|
| $BV_{DSS}$   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V, I_D=250\mu A$                      | 40   | ---  | ---       | V         |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V, I_D=15A$                          | ---  | 4.7  | 6.5       | $m\Omega$ |
|              |                                                | $V_{GS}=4.5V, I_D=15A$                         | ---  | 7.5  | 10.5      |           |
| $V_{GS(th)}$ | Gate Threshold Voltage                         | $V_{GS}=V_{DS}, I_D=250\mu A$                  | 1.2  | 1.9  | 2.2       | V         |
| $I_{DSS}$    | Drain-Source Leakage Current                   | $V_{DS}=32V, V_{GS}=0V, T_J=25^\circ\text{C}$  | ---  | ---  | 1         | $\mu A$   |
|              |                                                | $V_{DS}=32V, V_{GS}=0V, T_J=55^\circ\text{C}$  | ---  | ---  | 5         |           |
| $I_{GSS}$    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V, V_{DS}=0V$                    | ---  | ---  | $\pm 100$ | nA        |
| $R_g$        | Gate Resistance                                | $V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$          | ---  | 1.9  | ---       | $\Omega$  |
| $Q_g$        | Total Gate Charge                              | $V_{DS}=20V, V_{GS}=10V, I_D=15A$              | ---  | 19.8 | ---       | nC        |
| $Q_{gs}$     | Gate-Source Charge                             |                                                | ---  | 3.9  | ---       |           |
| $Q_{gd}$     | Gate-Drain Charge                              |                                                | ---  | 4.7  | ---       |           |
| $T_{d(on)}$  | Turn-On Delay Time                             | $V_{DD}=20V, V_{GS}=10V, R_G=3\Omega, I_D=15A$ | ---  | 11.5 | ---       | ns        |
| $T_r$        | Rise Time                                      |                                                | ---  | 9.2  | ---       |           |
| $T_{d(off)}$ | Turn-Off Delay Time                            |                                                | ---  | 23.8 | ---       |           |
| $T_f$        | Fall Time                                      |                                                | ---  | 15.4 | ---       |           |
| $C_{iss}$    | Input Capacitance                              | $V_{DS}=20V, V_{GS}=0V, f=1\text{MHz}$         | ---  | 1078 | ---       | pF        |
| $C_{oss}$    | Output Capacitance                             |                                                | ---  | 483  | ---       |           |
| $C_{rss}$    | Reverse Transfer Capacitance                   |                                                | ---  | 49   | ---       |           |

**Diode Characteristics**

| Symbol   | Parameter                              | Conditions                                | Min. | Typ. | Max. | Unit |
|----------|----------------------------------------|-------------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1</sup> | $V_G=V_D=0V$ , Force Current              | ---  | ---  | 45   | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>     | $V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$ | ---  | ---  | 1.2  | V    |

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=37A$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

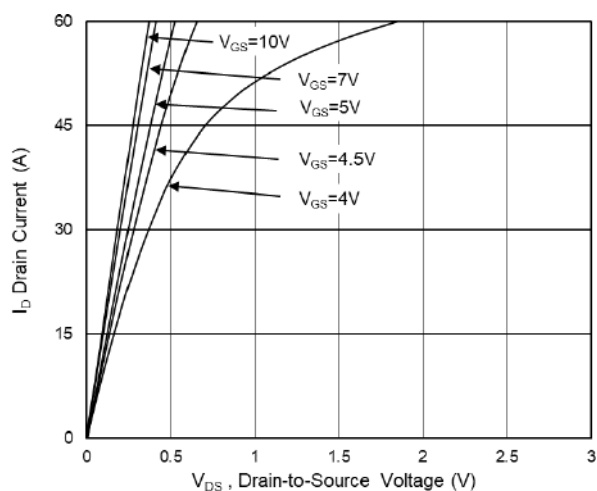


Fig.1 Typical Output Characteristics

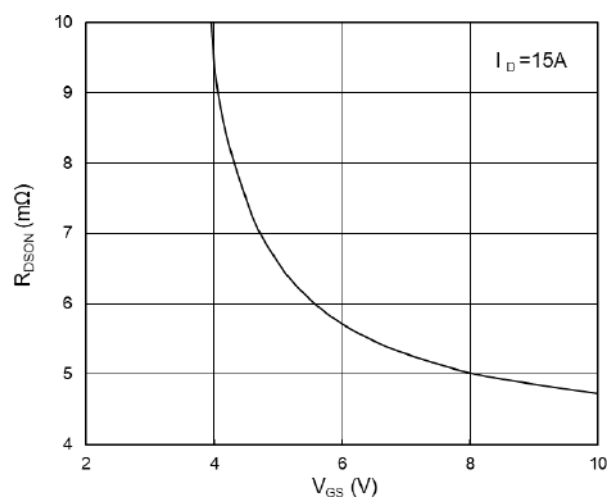


Fig.2 On-Resistance vs G-S Voltage

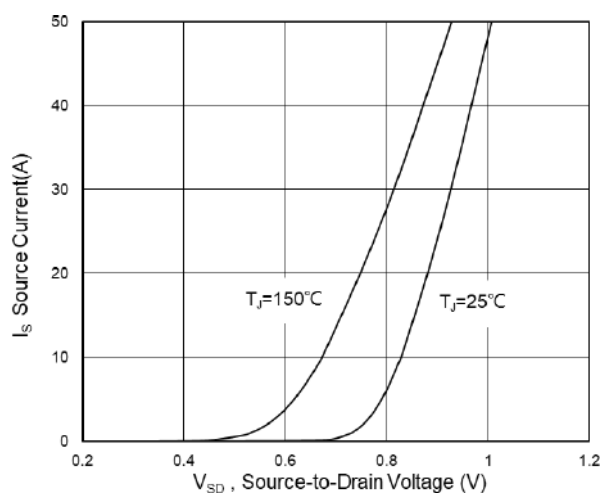


Fig.3 Source Drain Forward Characteristics

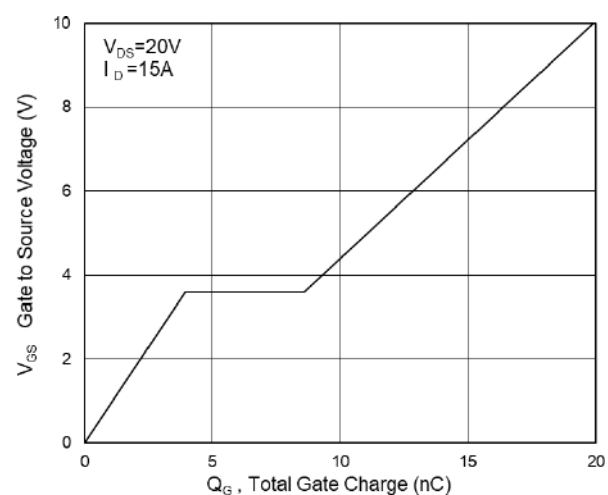


Fig.4 Gate-Charge Characteristics

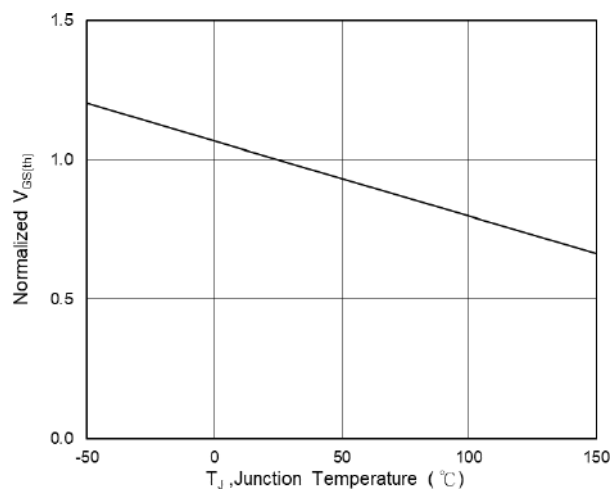


Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$

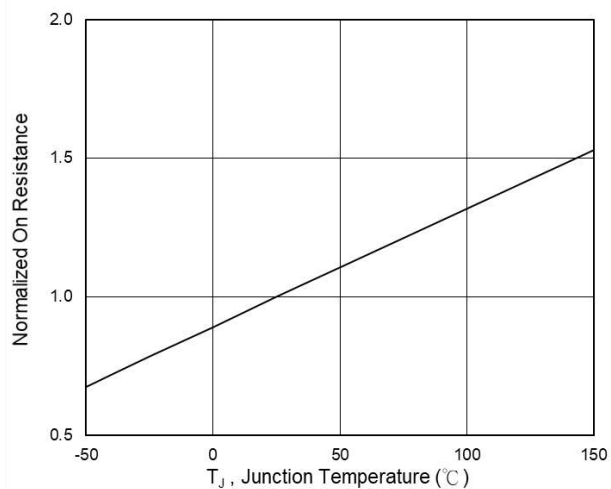
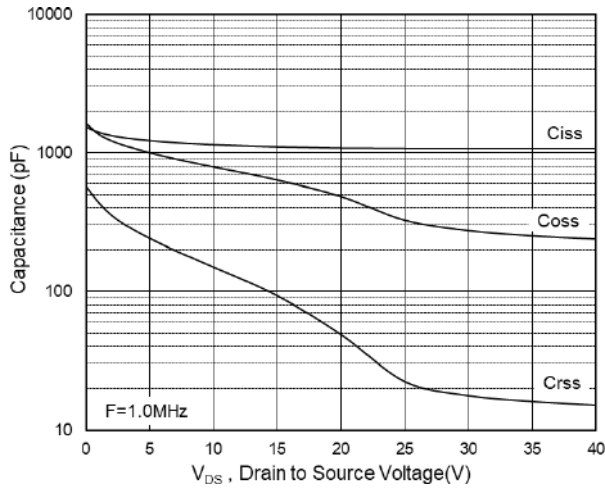
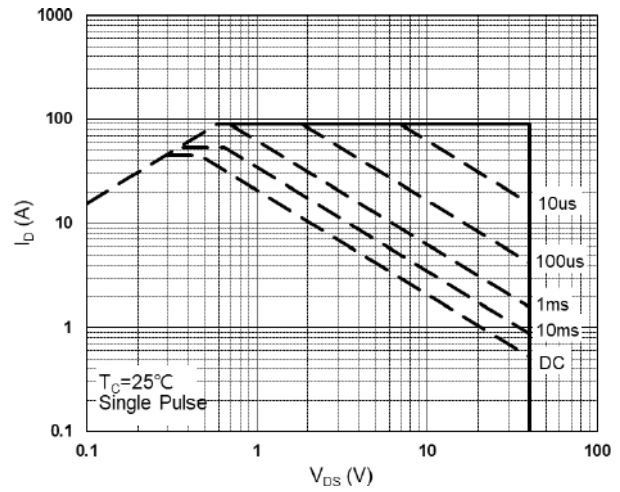


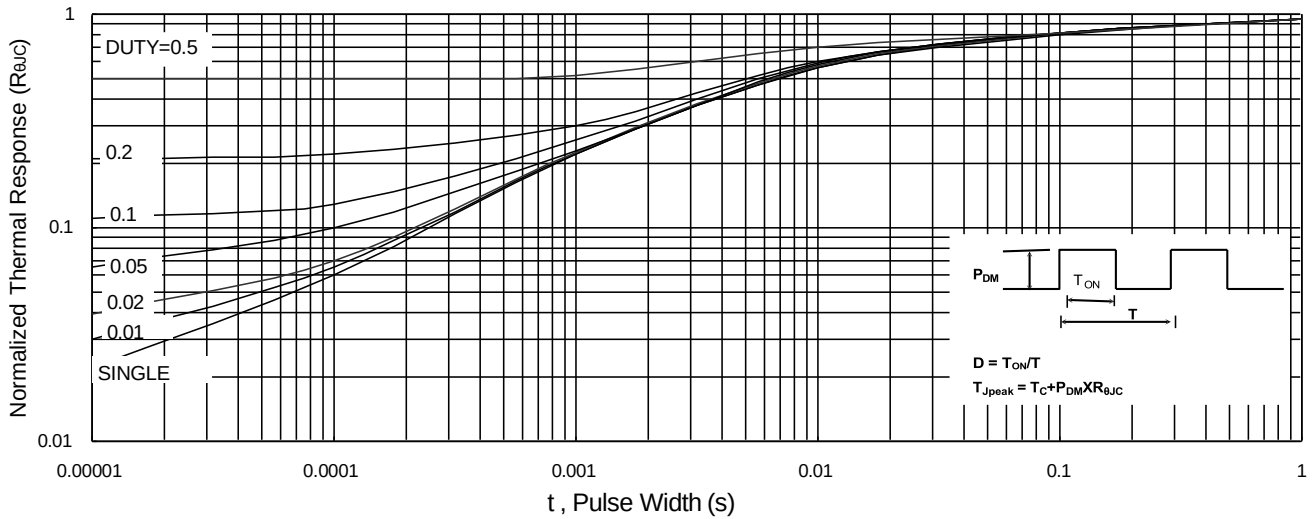
Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$



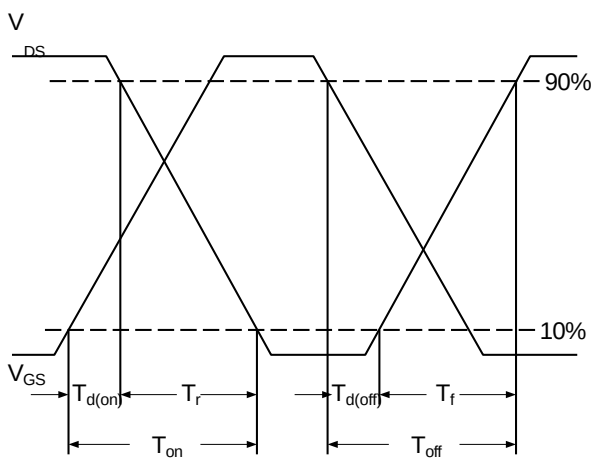
**Fig.7 Capacitance**



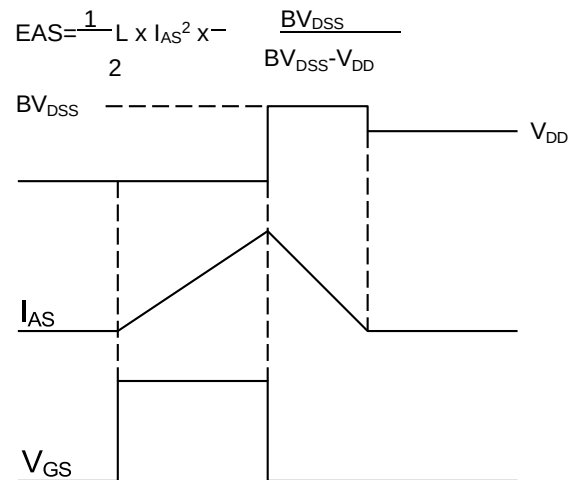
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**